DDR Termination Regulator

General Description

The RT9088 is a sink/source tracking termination regulator. It is specifically designed for low-cost and low-external component count systems. The RT9088 possesses a high speed operating amplifier that provides fast load transient response and only requires a minimum $30\mu F$ ceramic output capacitor. The RT9088 supports remote sensing functions and all features required to power the DDRIII and Low Power DDRIII / DDRIV VTT bus termination according to the JEDEC specification. In addition, the RT9088 provides an open-drain PGOOD signal to monitor the output regulation and an EN signal that can be used to discharge VTT during S3 (suspend to RAM) for DDR applications.

The RT9088 is available in the thermal efficient package, WDFN-10L 3x3.

Marking Information

63=YM DNN 63= : Product Code YMDNN : Date Code

Features

VIN Input Voltage Range: 1.1V to 3.5V
VCNTL Input Voltage Range: 2.9V to 5.5V

• Support Ceramic Capacitors

• Power Good Indicator

• 10mA Source/Sink Reference Output

• Meet DDRI, DDRII JEDEC Spec

 Support DDRIII, Low Power DDRIII/DDRIV VTT Applications

Soft-Start Function

• UVLO and OCP Protection

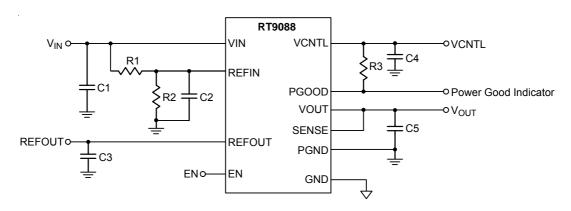
Thermal Shutdown

Applications

• Notebook/Desktop/Server

 Telecom/Datacom, GSM Base Station, LCD-TV/PDP-TV, Copier/Printer, Set-Top Box

Simplified Application Circuit



RT9088

Ordering Information

RT9088 □□

Package Type

QW: WDFN-10L 3x3 (W-Type)

Lead Plating System

G: Green (Halogen Free and Pb Free)

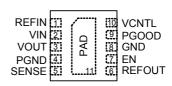
Note:

Richtek products are:

- ▶ RoHS compliant and compatible with the current requirements of IPC/JEDEC J-STD-020.
- ▶ Suitable for use in SnPb or Pb-free soldering processes.

Pin Configuration

(TOP VIEW)

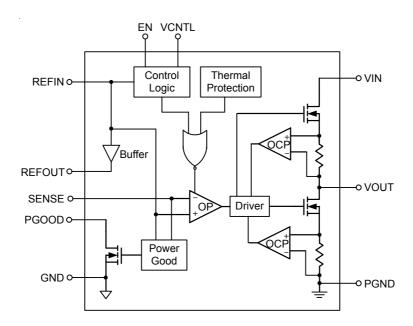


WDFN-10L 3x3

Functional Pin Description

Pin No.	Pin Name	Pin Function
1	REFIN	Reference input.
2	VIN	Power input of the regulator.
3	VOUT	Power output of the regulator.
4	PGND	Power ground of the regulator.
5	SENSE	Voltage sense input for the regulator. Connect to positive terminal of the output capacitor or the load.
6	REFOUT	Reference output. Connect to GND through a 0.1µF ceramic capacitor.
7	EN	Enable control input. For DDR VTT application, connect EN to SLP_S3. For other applications, use EN as the ON/OFF function.
9	PGOOD	Power good open-drain output. Connect a pull-up resistor between this pin and VCNTL pin.
10	VCNTL	Control voltage input. Connect this pin to the 3.3V or 5V power supply. A 4.7 μF ceramic decoupling capacitor is required.
8	GND	Analog ground. Connect to negative terminal of the output capacitor.
11 (Exposed Pad)	PAD	Exposed pad. The exposed pad is internally unconnected and must be soldered to a large PGND plane. Connect this PGND plane to other layers with thermal vias to help dissipate heat from the device.

Functional Block Diagram



Operation

The RT9088 is a linear sink/source DDR termination regulator with current capability up to 3A. The RT9088 builds in a high-side N-MOSFET which provides current sourcing and a low-side N-MOSFET which provides current sinking. All the control circuits are supplied by the power VCNTL. In normal operation, the error amplifier OP adjusts the gate driving voltage of the power MOSFET to achieve SENSE voltage well tracking the REFIN voltage.

Both the source and sink currents are detected by the internal sensing resistor, and the OCP function will work to limit the current to a designed value when overload happens. Furthermore, the current will be folded back to be one half if VOUT is out of the power good window.

Buffer

This function provides REFOUT output level which is equal to REFIN level with 10mA source/sink current capability.

Power Good

When the SENSE voltage is in the power good window and lasts for a certain delay time, then the PGOOD pin will be high impedance and the PGOOD voltage will be pulled high by the external resistor.

Control Logic

This block includes VCNTL UVLO, REFIN UVLO and Enable/Disable functions, and provides logic control to the whole chip.

Over-Current Protection

The device continuously monitors the output current to protect the pass transistor against abnormal operations. The current limit (I_{LIM}) level reduces by one-third when the output voltage is not within the powergood window. This reduction is a non-latch protection.

Thermal Protection

Both the high-side and low-side power MOSFETs will be turned off when the junction temperature is higher than typically 160°C, and be released to normal operation when junction temperature falls below 120°C typically.

RT9088

Absolute Maximum Ratings (Note 1)

• Supply Voltage, VIN, VCNTL	0.3V to 6V
• Input Voltage, EN, REFIN, SENSE	0.3V to 6V
Output Voltage, VOUT, REFOUT, PGOOD	0.3V to 6V
• Power Dissipation, P _D @ T _A = 25°C	
WDFN-10L 3x3	3.27W
Package Thermal Resistance (Note 2)	
WDFN-10L 3x3, θ_{JA}	30.5°C/W
WDFN-10L 3x3, θ_{JC}	7.5°C/W
• Lead Temperature (Soldering, 10 sec.)	260°C
• Junction Temperature	150°C
Storage Temperature Range	65°C to 150°C
• ESD Susceptibility (Note 3)	
HBM (Human Body Model)	2kV
Recommended Operating Conditions (Note 4)	
. •	
Control Input Voltage, VCNTL	2.9V to 5.5V

Electrical Characteristics

 $(V_{IN}$ = 1.5V, V_{EN} = V_{CNTL} = 3.3V, V_{REFIN} = V_{SENSE} = 0.75V, C_{OUT} = 10 μ F x 3, T_A = 25°C, unless otherwise specified)

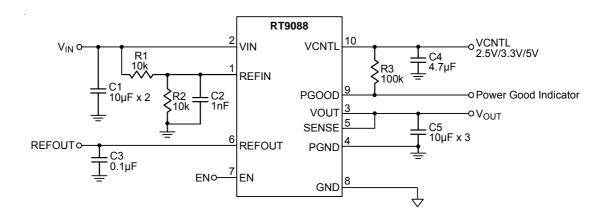
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Supply Current							
VCNTL Supply Current	IVCNTL	V _{EN} = V _{CNTL} , no load		0.7	1	mA	
VCNTL Shutdown Current	ISHDN_VCNTL	V _{EN} = 0V, V _{REFIN} = 0V, no load		65	80	μΑ	
		V _{EN} = 0V, V _{REFIN} > 0.4V, no load		200	400	μΑ	
VIN Supply Current	I _{VIN}	V _{EN} = V _{CNTL} , no load		1	50	μΑ	
VIN Shutdown Current	Ishdn_vin	V _{EN} = 0V, no load		0.1	50	μА	
Output							
VTT Output Voltage	Vout	V _{IN} = 1.5V, V _{REFIN} = 0.75V, I _{OUT} = 0A		0.75		V	
		V _{IN} = 1.35V, V _{REFIN} = 0.675V, I _{OUT} = 0A		0.675		V	
		V_{IN} = 1.2V, V_{REFIN} = 0.6V, I_{OUT} = 0A		0.6		V	
		I _{OUT} = ±2A, V _{LDOIN} = 1.5V, V _{REFOUT} = 0.75V	-25		25		
REFIN, VTT Output Voltage Offset	Vout_os	I _{OUT} = ±2A, V _{LDOIN} = 1.35V, V _{REFOUT} = 0.675V	-25		25	mV	
		I _{OUT} = ±2A, V _{LDOIN} = 1.2V, V _{REFOUT} = 0.6V	-25		25		

Parameter		Symbol	Test Conditions	Min	Тур	Max	Unit	
VOUT Source Cur	rent Limit	ILIM_VOUT_SR	VOUT in PGOOD window	3.5		5.5	Α	
VOUT Sink Currer	k Current Limit I _{LIM_VOUT_SK} VOUT in PGOOD window		3.5		5.5	Α		
VOUT Discharge Resistance		RDISCHARGE	$V_{REFIN} = 0V$, $V_{OUT} = 0.3V$, $V_{EN} = 0V$		18	25	Ω	
Power Good Con	nparator							
PGOOD Threshold			V _{SENSE} lower threshold with respect to REFOUT	-25	-20	-15		
		VTH_PGOOD	V _{SENSE} upper threshold with respect to REFOUT	15	20	25		
			PGOOD Hysteresis	5				
PGOOD Start-Up	Delay	T _{PGDELAY1}	Start-up rising delay, V _{SENSE} within PGOOD range		2		ms	
Output Low Voltage	je	V _{LOW_PGOOD}	I _{PGOOD} = 4mA			0.4	V	
PGOOD Falling D	elay	T _{PGDELAY2}	Falling delay, V _{SENSE} is out of PGOOD range		10		μS	
Leakage Current		ILEAKAGE _PGOOD	V _{SENSE} = V _{REFIN} (PGOOD high impedance), V _{PGOOD} = V _{IN} + 0.3V			1	μА	
REFIN and REFO	UT							
REFIN Input Curre	ent	I _{REFIN}	V _{EN} = V _{CNTL}			1	μΑ	
REFIN Voltage Range		VREFIN		0.5		1.8	V	
REFIN Under-Voltage		Ving o Been	REFIN rising 360		390	420	mV	
Lockout		Vuvlo_refin	Hysteresis	20			IIIV	
REFOUT Voltage Tolerance to VREFIN		VTOL_REFOUT	-10mA < I _{REFOUT} < 10mA, V _{REFIN} = 0.75V	-15		15	mV	
			-10mA < I _{REFOUT} < 10mA, V _{REFIN} = 0.675V	-15		15		
			-10mA < I _{REFOUT} < 10mA, V _{REFIN} = 0.6V	-15	5 15			
REFOUT Source Current Limit		ILIM_REFOUT_SR	V _{REFOUT} = 0V	10	40		mA	
REFOUT Sink Current Limit		ILIM_REFOUT_SK	V _{REFOUT} = REFIN + 1V	10	40		mA	
UVLO/EN								
UVLO Threshold		Vuvlo_vcntl	Rising	2.5	2.7	2.85	V	
			Hysteresis 12		120		mV	
pat	_ogic-High	V _{IN_H}		1.7			-	
Voltage [_ogic-Low	VIN_L				0.3	\Box	
Thermal Shutdov	vn	1		T	I	•		
Thermal Shutdow	n	T _{SD}	Shutdown temperature		160		°C	
Threshold		- 55	Hysteresis		15			

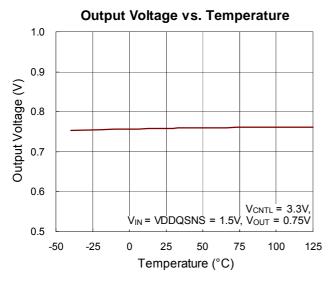
RT9088

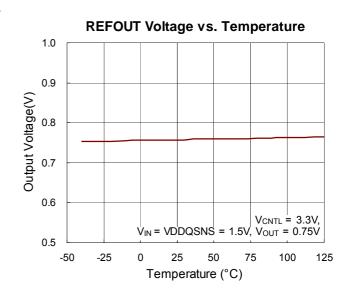
- **Note 1.** Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions may affect device reliability.
- Note 2. θ_{JA} is measured at T_A = 25°C on a high effective thermal conductivity four-layer test board per JEDEC 51-7. θ_{JC} is measured at the exposed pad of the package.
- Note 3. Devices are ESD sensitive. Handling precaution is recommended.
- Note 4. The device is not guaranteed to function outside its operating conditions.

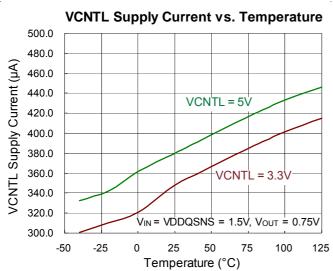
Typical Application Circuit

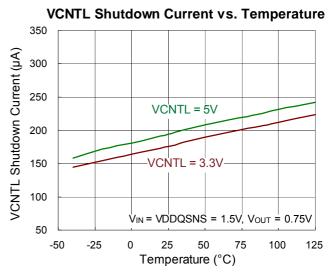


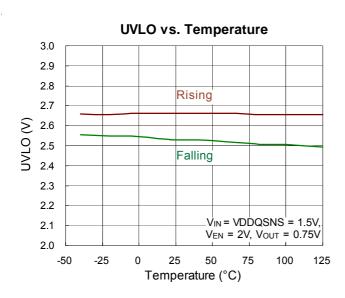
Typical Operating Characteristics

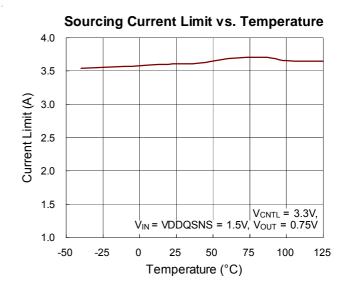


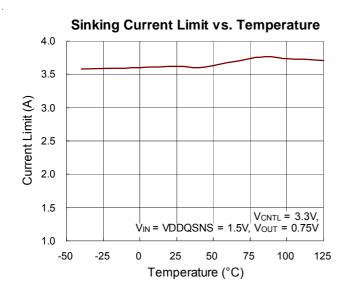


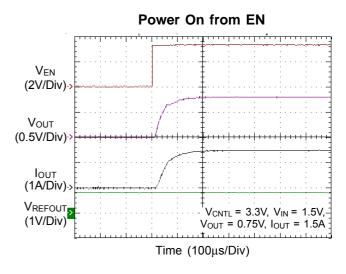


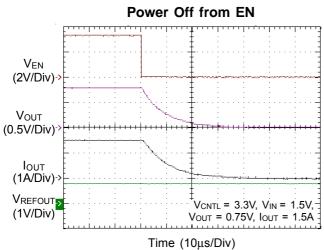


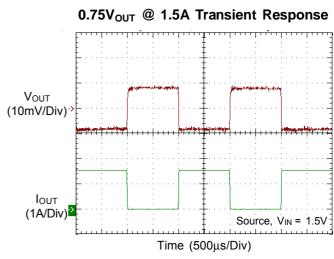


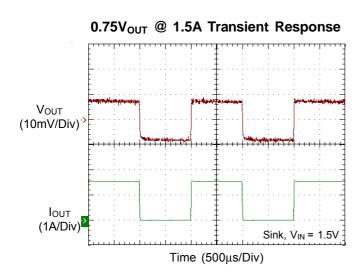












Application Information

The RT9088 is a 3A sink/source tracking termination regulator. It is specifically designed for low-cost and low-external component count system such as notebook PC applications.

Capacitor Selection

Good bypassing is recommended from VIN to GND to help improve AC performance. A $10\mu F$ or greater input capacitor placed as close as possible to the IC is recommended. The input capacitor must be placed at a distance of less than 0.5 inches from the VIN pin of the IC.

the $1\mu F$ ceramic capacitor added close to the VCNTL pin should be kept away from any parasitic impedance from the supply power. For stable operation, the total capacitance of the ceramic capacitor at the VOUT output terminal must be larger than $30\mu F$. The RT9088 is designed specifically to work with low ESR ceramic output capacitor in space saving and performance consideration. Larger output capacitance can reduce the noise and improve load transient response, stability and PSRR. The output capacitor should be located near the VOUT output terminal pin as close as possible.

Thermal Considerations

For continuous operation, do not exceed absolute maximum junction temperature. The maximum power dissipation depends on the thermal resistance of the IC package, PCB layout, rate of surrounding airflow, and difference between junction and ambient temperature. The maximum power dissipation can be calculated by the following formula:

$$P_{D(MAX)} = (T_{J(MAX)} - T_A) / \theta_{JA}$$

where $T_{J(MAX)}$ is the maximum junction temperature, T_A is the ambient temperature, and θ_{JA} is the junction to ambient thermal resistance.

For recommended operating condition specifications, the maximum junction temperature is 125°C. The junction to ambient thermal resistance, θ_{JA} , is layout dependent. For WDFN-10L 3x3 package, the thermal resistance, θ_{JA} , is 30.5°C/W on a standard JEDEC 51-7 four-layer thermal test board. The maximum power dissipation at T_A = 25°C can be calculated by the following formula :

 $P_{D(MAX)} = (125^{\circ}C - 25^{\circ}C) / (30.5^{\circ}C/W) = 3.27W$ for WDFN-10L 3x3 package

The maximum power dissipation depends on the operating ambient temperature for fixed $T_{J(MAX)}$ and thermal resistance, θ_{JA} . The derating curve in Figure 1 allows the designer to see the effect of rising ambient temperature on the maximum power dissipation.

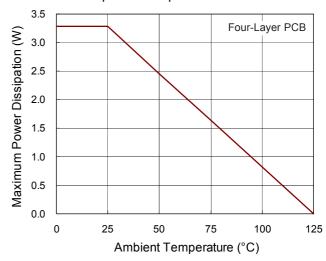
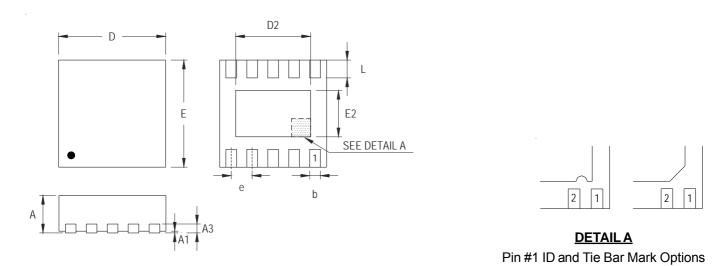


Figure 1. Derating Curve of Maximum Power Dissipation

Outline Dimension



Note: The configuration of the Pin #1 identifier is optional, but must be located within the zone indicated.

Symbol	Dimensions I	n Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.700	0.800	0.028	0.031	
A1	0.000	0.050	0.000	0.002	
A3	0.175	0.250	0.007	0.010	
b	0.180	0.300	0.007	0.012	
D	2.950	3.050	0.116	0.120	
D2	2.300	2.650	0.091	0.104	
Е	2.950	3.050	0.116	0.120	
E2	1.500	1.750	0.059	0.069	
е	0.500		0.0)20	
L	0.350	0.450	0.014 0.018		